

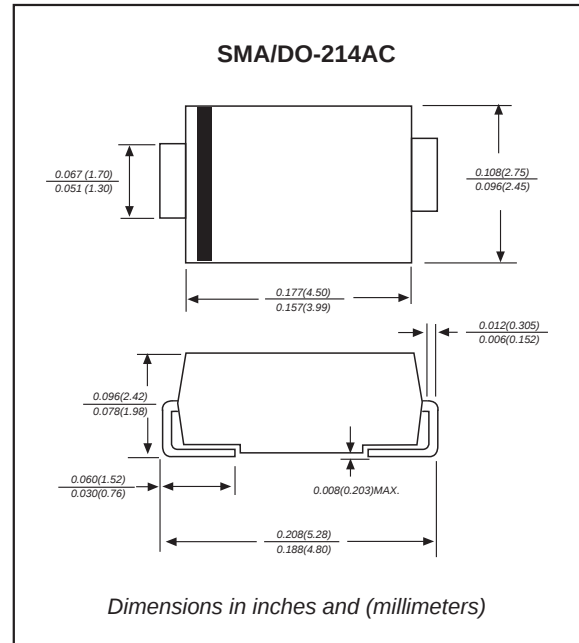
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at terminals
- ◆ Compliant to RoHS 2.0

Mechanical data

- ◆ **Case:** JEDEC DO-214AC molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any

Package outline

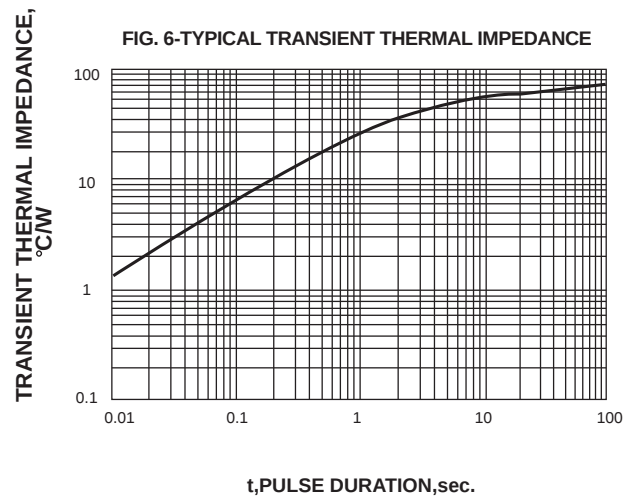
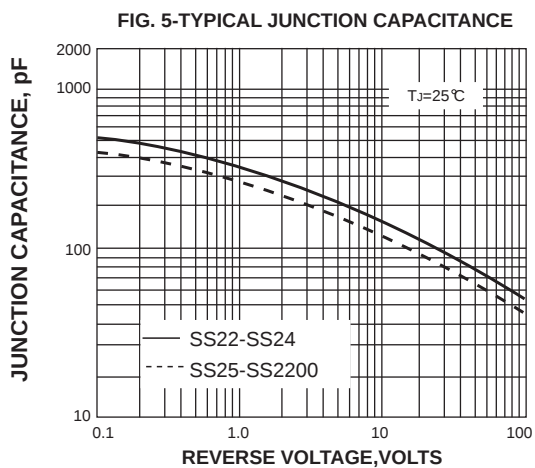
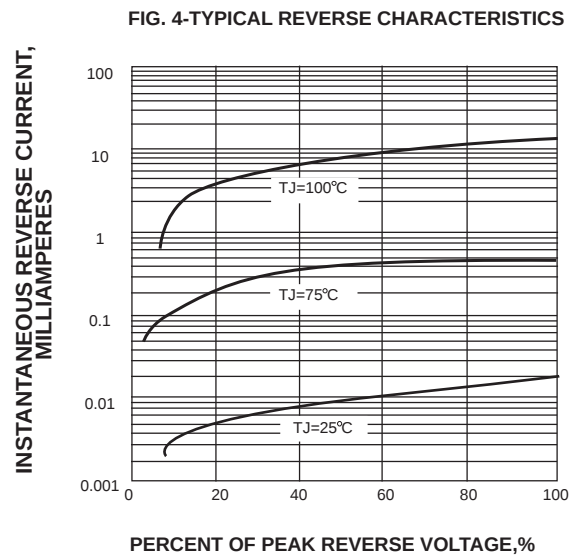
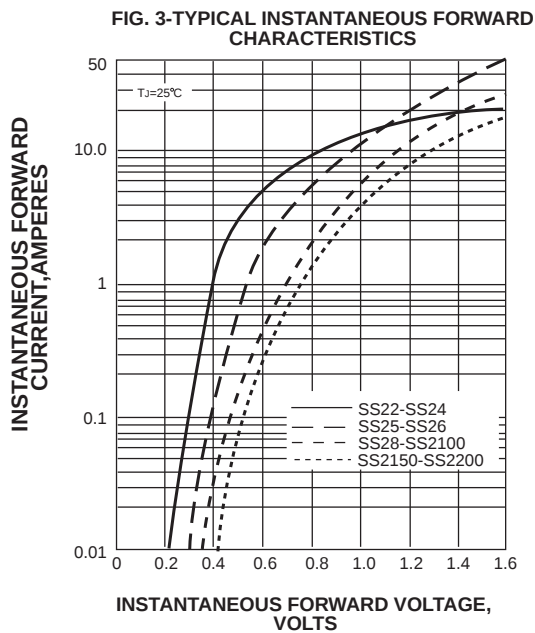
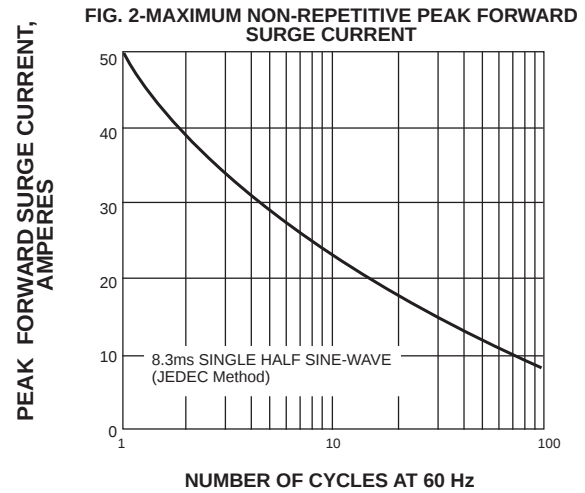
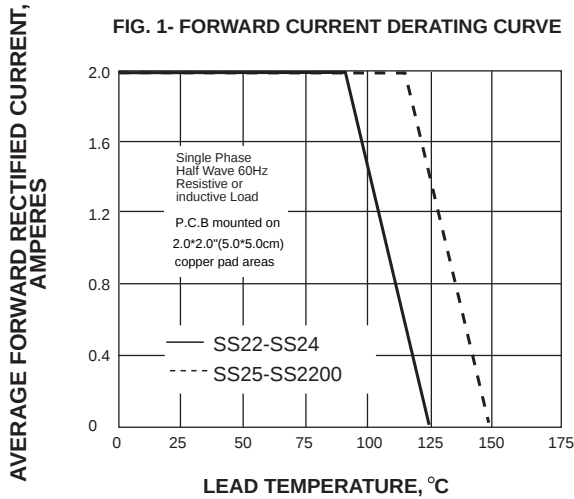


Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

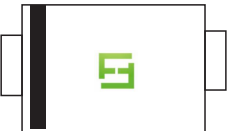
PARAMETER	SYMBOLS	SS22	SS23	SS24	SS25	SS26	SS28	SS2100	SS2150	SS2200	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at T _L (see fig.1)	I _(AV)	2.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	50.0									A
Maximum instantaneous forward voltage at 2.0A	V _F	0.55			0.70		0.85		0.95		V
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =100°C	I _R	0.5					0.1			mA	
		10.0					5.0		2.0		
Typical junction capacitance (NOTE 1)	C _J	220									pF
Typical thermal resistance (NOTE 2)	R _{θJA}	80									°C/W
Operating junction temperature range	T _J	-55 to +125				-55 to +150					°C
Storage temperature range	T _{STG}	-55 to +150									°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

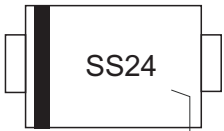
Rating and characteristic curves



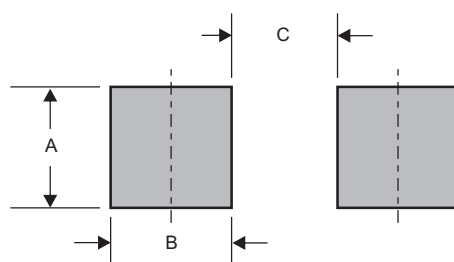
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
SS22	SS22	 SS24 Marking code
SS23	SS23	
SS24	SS24	
SS25	SS25	
SS26	SS26	
SS28	SS28	
SS2100	SS210	
SS2150	SS215	
SS2200	SS220	

Suggested solder pad layout

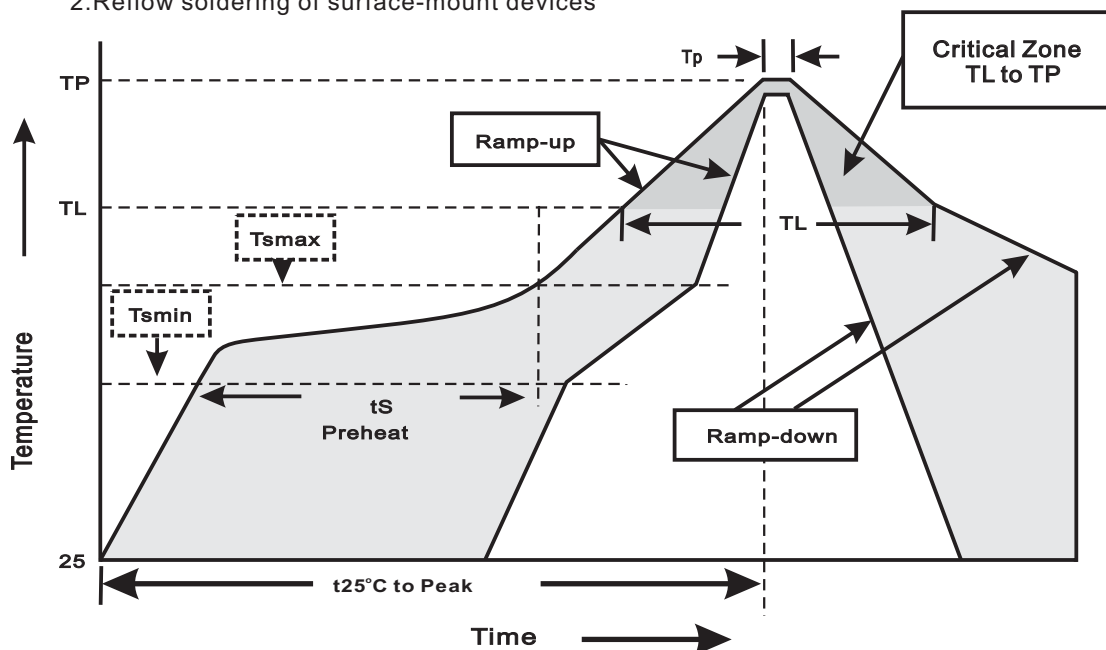


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{min}) -Temperature Max(T_{max}) -Time(min to max)(t_s)	150°C 200°C $60\sim 120\text{sec}$
T_{max} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C $60\sim 260\text{sec}$
Peak Temperature(T_P)	$255^{\circ}\text{C}-0/+5^{\circ}\text{C}$
Time within 5°C of actual Peak Temperature(t_P)	$10\sim 30\text{sec}$
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$